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#8/Amend ONE
Reply under 37 CFR 1.116 1. 7030

--Expedited Procedure--
Technology Center 2800

C. Moore

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Abbott, et al.

Serial No.: 09/733,718

Filed: 12/08/00

For: Leadframes for High Adhesion Semiconductor Devices and Method of
Fabrication

Docket No.: TI-29679

Examiner: Cao, Phat X.

Art Unit: 2814

Amendment under 37 CFR 1.116

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

12-16-02

Michael K. Skrehot

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the
Examiner's Office Action dated 10/15/02. They are respectfully submitted as a
full and complete response to that Action.

Please amend the above-referenced application as follows:

In the Claims

21. (amended) A semiconductor device, comprising:
a leadframe, comprising:
a first layer of noble metal covering said leadframe; and

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1/10/03

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